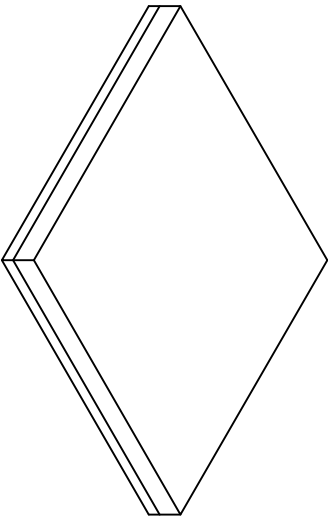


01/29/01 1:10:04 PM (Drawing) - Released to 8

REV	DESCRIPTION	DATE	BY
00	INITIAL RELEASE PER DGN C8492	03/28/00	ADEBO
01	ADDED 176 FOOTPRINT, UPDATED FORMAT	01/29/01	GREME



7. REFERENCE SPECIFICATIONS:
 A. AWM SPEC #001-0531-2234; PACKING OPERATION PROCEDURE.
 B. AWM SPEC #001-0519-2092; MARKING.
6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
5. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 196.
4. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 14 X 14.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION	
XXXXX	XXXXX	DATE	DATE
XXXXX	XXXXX	03/15/00	03/15/00
XXXXX	XXXXX	03/15/00	03/15/00
XXXXX	XXXXX	03/15/00	03/15/00
XXXXX	XXXXX	03/28/00	03/28/00
APPROVALS DESIGNED: ADEBO CHECKED: DARNO PRODUCT MANAGER: TPANC DRAWN: N/A DO NOT SCALE DRAWING		TITLE: PACKAGE OUTLINE - MAF, 14 X 14 MATRIX, 15.00mm X 15.00mm X 1.40mm, 0.70mm MOLD CAP, 0.48mm BALL, 1.00mm PITCH, LAMINATE SUBSTRATE, AWM SIZE: A3 SHEET NO.: 79169 TOTAL SHEETS: 1 OF 3	



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